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<u>DISTRIBUTION STATEMENT A</u>. Approved for public release; distribution is unlimited.

5962-E688-92

#### SCOPE

- 1.1 <u>Scope</u>. This drawing describes device requirements for class B microcircuits in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices".
  - 1.2 Part or Identifying Number (PIN). The complete PIN shall be as shown in the following example:



1.2.1 <u>Device type(s)</u>. The device type(s) shall identify the circuit function as follows:

Device type Generic number

# Circuit function

01

54HCT574

Octal D-type edge-triggered flip-flop, three-state outputs, TTL compatible inputs

1.2.2 <u>Case outline(s)</u>. The case outline(s) shall be as designated in MIL-STD-1835 and as follows:

Outline letter	Descriptive designator	<u>Terminals</u>	Package style
R	GDIP1-T20 or CDIP2-T20	20	Dual-in-line
2	CQCC1-N20	20	Square leadless chip carrier

1.2.3 <u>Lead finish</u>. The lead finish shall be as specified in MIL-M-38510. Finish letter "X" shall not be marked on the microcircuit or its packaging. The "X" designation is for use in specifications when lead finishes A, B, and C are considered acceptable and interchangeable without preference.

1.3 Absolute maximum ratings. 1/2/3/

Supply voltage range ( $V_{CC}$ )	-0.5 V dc to +7.0 V dc
DC input voltage $(V_{***})^{**}$	-0.5 V dc to V <sub>CC</sub> +0.5 V dc
DC output voltage (VONT)	-0.5 V dc to V <sub>CC</sub> +0.5 V dc
Input clamp current $(Y_{1K})$ $(V_{1N} < 0.0 \text{ V}, V_{1N} > V_{CC})$	±20 mA
DC output voltage ( $V_{OUT}$ )	±20 mA
DC output current (I <sub>OHT</sub> ) (V <sub>OHT</sub> = 0 to V <sub>CC</sub> ) (per output)	±35 mA
DC $V_{CC}$ or GND current ( $I_{CC}$ or $I_{GND}$ ) (per pin)	±70 mA
Storage temperature range	-65°C to +150°C
Maximum power dissipation (PD)	500 mW <u>4</u> /
Lead temperature (soldering, 10 seconds)	+265°C
Thermal resistance, junction-to-case $(\theta_{JC})$ Junction temperature $(T_J)$	See MIL-STD-1835
Junction temperature (I <sub>J</sub> )	+175°C
case operating temperature (I <sub>C</sub> )	-55°C to +125°C

 $\underline{4}$ / For  $T_C$  = +100°C to +125°C, derate linearly at 8 mW/°C.

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<sup>1/</sup> Stresses above the absolute maximum rating may cause permanent damage to the device. Extended operation at the maximum levels may degrade performance and affect reliability.

<sup>2/</sup> Unless otherwise specified, all voltages are referenced to ground.
3/ The limits for the parameters specified herein shall apply over the full specified V<sub>CC</sub> range and case temperature range of -55°C to +125°C.

1.4 Recommended operating conditions. 1/2/			
Supply voltage ( $V_{CC}$ )	, 0.9V <sub>CC</sub> to 0.1V <sub>C</sub>	+4.5 V	dc
2. APPLICABLE DOCUMENTS			
2.1 <u>Government specification, standards, and bulletin.</u> standards, and bulletin of the issue listed in that issue Standards specified in the solicitation, form a part of the specified in the solicitation.	of the Departmen	t of Defense Index of Sp	ecifications and
SPECIFICATION			
MILITARY			
MIL-M-38510 - Microcircuits, General Specific	ation for.		
STANDARDS			
MILITARY			
MIL-STD-883 - Test Methods and Procedures for MIL-STD-1835 - Microcircuit Case Outlines.	Microelectronics	•	
BULLETIN			
MILITARY			
MIL-BUL-103 - List of Standardized Military D	rawings (SMD's).		
(Copies of the specification, standards, and bulletin reacquisition functions should be obtained from the contract	equired by manufacting activity or a	cturers in connection wi as directed by the contr	th specific acting activity.)
2.2 <u>Non-Government publications</u> . The following documen herein. Unless otherwise specified, the issues of the document of the DODISS cited in the solicitation. Unless otherwise are the issues of the documents cited in the solicitation.	cuments which are specified, the	DoD adopted are those 1	isted in the issue
ELECTRONIC INDUSTRIES ASSOCIATION (EIA)			
JEDEC Standard No. 7-A - Standardized for Description CMOS Devices.	of 54/74HCXXXX a	and 54/74HCTXXXX High-Sp	eed
(Applications for copies should be addressed to the Elec Washington, DC 20006.)	ctronics Industri	es Association, 2001 Eye	Street, NW,
2.3 Order of precedence. In the event of a conflict be herein, the text of this drawing shall take precedence.	etween the text of	f this drawing and the r	eferences cited
1/ Unless otherwise specified, all voltages are reference. 2/ The limits for the parameters specified herein shall range of -55°C to +125°C.	ed to ground. apply over the fu	all specified V <sub>CC</sub> range	and case temperature
STANDARDIZED MILITARY DRAWING	SIZE		5962-89742
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# 3. REQUIREMENTS

- 3.1 <u>Item requirements</u>. The individual item requirements shall be in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices" and as specified herein.
- 3.2 <u>Design, construction, and physical dimensions</u>. The design, construction, and physical dimensions shall be as specified in MIL-M-38510 and herein.
  - 3.2.1 <u>Case outline(s)</u>. The case outline(s) shall be in accordance with 1.2.2 herein.
  - 3.2.2 <u>Terminal connections</u>. The terminal connections shall be as specified on figure 1.
  - 3.2.3 <u>Truth table</u>. The truth table shall be as specified on figure 2.
  - 3.2.4 Logic diagram. The logic diagram shall be as specified on figure 3.
  - 3.2.5 Switching waveforms. The switching waveforms shall be as specified on figure 4.
- 3.3 <u>Electrical performance characteristics</u>. Unless otherwise specified herein, the electrical performance characteristics are as specified in table I and shall apply over the full case operating temperature range.
- 3.4 <u>Electrical test requirements</u>. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are described in table I.
- 3.5 <u>Marking</u>. Marking shall be in accordance with MIL-STD-883 (see 3.1 herein). The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's PIN may also be marked as listed in MIL-BUL-103 (see 6.6 herein).
- 3.6 <u>Certificate of compliance</u>. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-BUL-103 (see 6.6 herein). The certificate of compliance submitted to DESC-EC prior to listing as an approved source of supply shall affirm that the manufacturer's product meets the requirements of MIL-STD-883 (see 3.1 herein) and the requirements herein.
- 3.7 <u>Certificate of conformance</u>. A certificate of conformance as required in MIL-STD-883 (see 3.1 herein) shall be provided with each lot of microcircuits delivered to this drawing.
- 3.8 Notification of change. Notification of change to DESC-EC shall be required in accordance with MIL-STD-883 (see 3.1 herein).
- 3.9 <u>Verification and review</u>. DESC, DESC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.

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Test and MIL-STD-883 test	Symbo 1	Conditions -55°C ≤ T <sub>C</sub> ≤ +12	Devic 5°C type	•	Group A subgroups	Limits		Uni
method		$ \begin{array}{c c} -55^{\circ}C \leq T_{C} \leq +12! \\ 4.5 \text{ V} \leq V_{CC} \leq 5.! \\ \text{unless otherwise spec} \end{array} $				Min	Max	•
High level output voltage 3006	V <sub>OH1</sub> 1/	For all inputs affect output under test VIN = VIH or VIL VIH = 2.0 V VIL = 0.8 V For all other inputs VIN = VCC or GND IOH = -20 µA	ing All	4.5 V	1,2,3	4.4		V
	v <sub>OH2</sub>	For all inputs affect output under test  VIN = VIH or VIL  VY = 2.0 V	ing All	4.5 V	1	3.98		٧
		VIN = VIH OF VIL VIH = 2.0 V VIL = 0.8 V For all other inputs VIN = V <sub>CC</sub> or GND I <sub>OH</sub> = -6.0 mA			2,3	3.7		
Low level output voltage 3007	V <sub>OL1</sub> <u>1</u> /	For all inputs affect output under test  VIN = VIH OF VIL  VIH = 2.0 V  VIL = 0.8 V  For all other inputs  VIN = VCC OF GND  IOL = 20 µA	ing All	4.5 V	1,2,3		0.1	V
output under test		For all inputs affects output under test VIN = VIH or VIL VIH = 2.0 V VIL = 0.8 V	ng All	11 4.5 V	1		0.26	٧
		VII = 0.8 V For all other inputs VIN = VCC or GND IOL = 6.0 mA			2,3		0.4	
nput current low 3009	IIL	For input under test  VIN = GND  For all other inputs	All	5.5 V	1		-0.1	μА
		For all other inputs  V <sub>IN</sub> = V <sub>CC</sub> or GND			2,3		-1.0	
nput current high 3010	IIH	For input under test  VIN = VCC For all other inputs	All	5.5 V	1		0.1	μA
		V <sub>IN</sub> = V <sub>CC</sub> or GND			2,3		1.0	
ee footnotes at end of	table.					-		
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Test and MIL-STD-883 test method	Symbol	Conditions   -55°C ≤ T <sub>C</sub> ≤ +12   4.5 V ≤ V <sub>CC</sub> ≤ 5.   unless otherwise spe	Device 5°C type 5 V	v <sub>cc</sub>	Group A subgroups	Li Min	mits     Max	Uni
Quiescent supply current output	Iccz	OC - GND For all other inputs	A11	5.5 V	1		8	μА
three-stated 3005		V <sub>IN</sub> - V <sub>CC</sub> or GND			2,3		160	
Quiescent supply current output high	Іссн	For all inputs V <sub>IN</sub> = V <sub>CC</sub> or GND	All	5.5 V	1		8	μΑ
3005					2,3		160	
Quiescent supply current output low	ICCL	For all inputs V <sub>IN</sub> = V <sub>CC</sub> or GND	All	5.5 V	1		8	μΑ
3005					2,3		160	
Additional quiescent supply current	ΔI <sub>CC</sub>	For input under test V <sub>IN</sub> = 2.4 V, 0.5 V For all other inputs	All	5.5 V	1	<del></del>	2.4	mA
	<u> </u>	V <sub>IN</sub> = V <sub>CC</sub> or GND			2,3		3.0	
Three-state output leakage current low	I <sub>OZL</sub>	OC = 0.8 V or 2.0 V For all other inputs	All	5.5 V	1		-0.5	μА
3020		V <sub>IN</sub> = V <sub>CC</sub> or GND For output under test V <sub>OUT</sub> = GND			2.3		-10.0	
Three-state output leakage current high	I <sub>OZH</sub>	OC = 0.8 V or 2.0 V For all other inputs	ATI	5.5 V	1		0.5	μΑ
3021		V <sub>IN</sub> = V <sub>CC</sub> or GND For output under test V <sub>OUT</sub> = V <sub>CC</sub>			2,3		10.0	
Input capacitance 3012	CIN	T <sub>C</sub> = +25°C See 4.3.1c	All	GND	4		10	pF
Output three-state capacitance 3012	Соит	T <sub>C</sub> = +25°C See 4.3.1c	All	5.5 V	4		20	pF
Power dissipation capacitance	C <sub>PD</sub> <u>3</u> /	T <sub>C</sub> = +25°C See 4.3.1c	All	5.0 V	4	ï	93	pF
Functional tests 3014		See 4.3.1d	All		7,8			
see footnotes at end of t	able.		1	<u> </u>				
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DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444				DEVICE	ON LEVEL	-	EET	<del></del>

Test and MIL-STD-883 test	Symbol	Conditions -55°C ≤ T <sub>C</sub> ≤ +125°C	Device type	v <sub>cc</sub>	Group A subgroups	Limits		Unit
method		$-55^{\circ}$ C ≤ T <sub>C</sub> ≤ +125°C 4.5 V ≤ V <sub>CC</sub> ≤ 5.5 V unless otherwise specified		*66		Min	Max	
Maximum clock frequency 3003	f <sub>MAX</sub>	C <sub>l</sub> = 50 pF minimum See figure 4	All	4.5 V	9	30		MHz
	<u>2</u> /				10,11	20		
Minimum high, low clock pulse width	t <sub>w</sub>		All	4.5 V	9		16	ns
	2/			:	10,11		24	
Minimum high, low setup time, nD to CLK1	t <sub>su</sub>		All	4.5 V	9		12	ns
	<u>2</u> /				10,11		18	
Minimum high, low hold time, nD from CLK	t <sub>h 2</sub> /		All	4.5 V	9,10,11		5	ns
Propagation delay time CLK to nQ	t <sub>PLH</sub> ,		All	4.5 V	9		33	ns
3003	'''-				10,11		50	
Output enable time OC to nQ	t <sub>PZL</sub> ,	C <sub>L</sub> = 50 pF minimum R <sub>L</sub> = 1 KΩ See figure 4	All	4.5 V	9		30	ns
3003		See figure 4			10,11		45	
Output disable time OC to nQ	t <sub>PLZ</sub> ,		All	4.5 V	9		28	ns
3003	1112				10,11		42	
Output transition time nQ	t <sub>TLH</sub> ,	C <sub>L</sub> = 50 pF minimum See figure 4	All	4.5 V	9		12	ns
nQ 3003	2/				10,11		18	

<sup>1/</sup> For a power supply of 5 V  $\pm 10\%$  the worst case output voltages ( $V_{OH}$  and  $V_{OL}$ ) occur for HCT at 4.5 V. Thus, the 4.5 V values should be used when designing with this supply. Worst cases  $V_{IH}$  and  $V_{IL}$  occur at  $V_{CC}$  = 5.5 V and 4.5 V respectively.

d = duty cycle

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<sup>2/</sup> Guaranteed, if not tested, to the limits specified in table I.

Power dissipation capacitance ( $C_{PD}$ ), determines the no load dynamic power consumption;  $P_D$  (total) =  $C_{PD}V_{CC}^2f$  + ( $V_{CC} \times I_{CC}$ ) + n ( $AI_{CC} \times V_{CC} \times d$ ), and the no load dynamic current consumption ( $I_S$ ) is  $I_S = C_{PD}V_{CC}^f + I_{CC}^c$  + nd $AI_{CC}$ . Where:  $P_D$  = dynamic power dissipation.  $C_{PD}$  = power dissipation capacitance of the device f = input switching frequency f = number of inputs switching f = duty cycle

Device type		0	1		
Case outline	es	R,2			
Terminal number	Terminal symbol	Terminal number	Terminal symbol		
1	<u>0C</u>	11	CLK		
2	1D	12	8Q		
3	<b>2</b> D	13	7Q		
4	3D	14	6Q		
5	4D	15	5Q		
6	5D	16	4Q		
7	6D	17	3Q		
8	7D	18	2Q		
9	8D	19	1Q		
10	GND	20	v <sub>cc</sub>		

Terminal symbol descriptions				
Terminal symbol	Description			
nD (n = 1 to 8)	Data inputs			
<u>oc</u>	Output enable control input (active low)			
nQ (n = 1 to 8)	Outputs (non-inverting)			
CLK	Clock pulse timing input (active rising edge)			

FIGURE 1. Terminal connections.

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Inputs		Output Q	
ōc	CLK	D	
L L H	t t L X	H L X	H L Qo Z

H = High voltage level
L = Low voltage level

L X Z

Immaterial

Z = High-impedance t = Low-to-high transition Q = Previous mQ before low-to-high transition of CLK

FIGURE 2. <u>Truth table</u>.

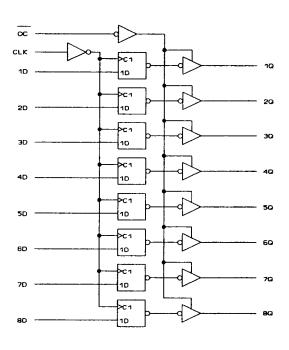
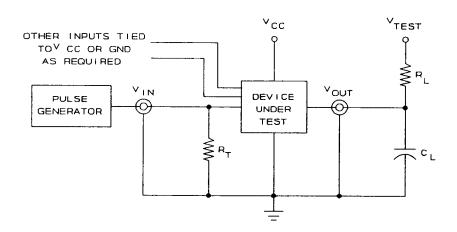


FIGURE 3. Logic diagram.

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### NOTES:

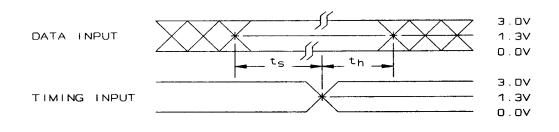
When measuring  $t_{PHZ}$  and  $t_{PZH}$ :  $V_{test}$  = GND
When measuring  $t_{PLZ}$  and  $t_{PZL}$ :  $V_{test}$  =  $V_{CC}$ When measuring  $t_{PLR}$  and  $t_{PLL}$ :  $V_{test}$  = open
The  $t_{PZL}$  and  $t_{PLZ}$  reference waveform is for the output under test with internal conditions such that the output is at  $V_{OL}$  except when disabled by the output enable control. The  $t_{PZH}$  and  $t_{PLZ}$  reference waveform is for the output under test with internal conditions such that the output is at  $V_{OH}$  except when disabled by the output enable control.

 $C_L$  = 50 pF minimum or equivalent (includes probe and jig capacitance)  $R_L$  = 1 KΩ or equivalent  $R_T$  = 50 Ω or equivalent Input signal from pulse generator:  $V_{IN}$  = 0.0 V to 3.0 V;  $t_r \le 6$  ns;  $t_f \le 6$  ns; duty cycle = 50 percent. This parameters shall be tested at a minimum input frequency of 1 MHz.

The outputs are measured one at a time with one transition per measurement.

FIGURE 4. Switching waveforms and test circuit.

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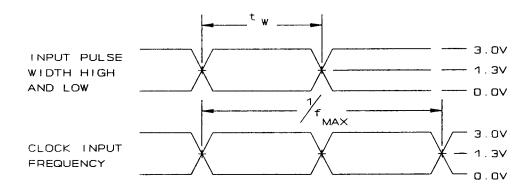
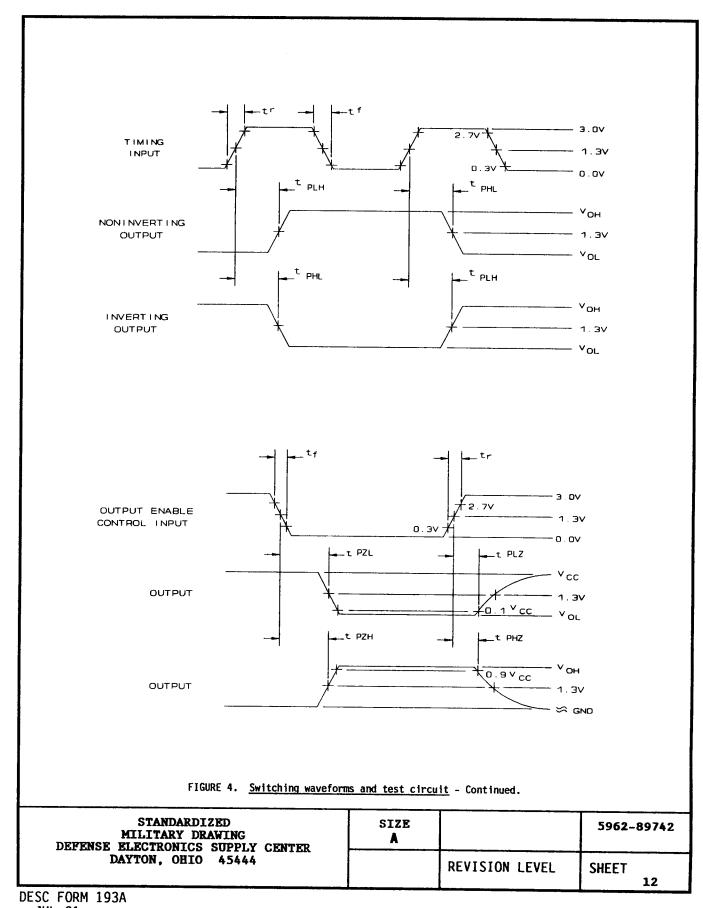


FIGURE 4. Switching waveforms and test circuit - Continued.

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#### 4. QUALITY ASSURANCE PROVISIONS

- 4.1 <u>Sampling and inspection</u>. Sampling and inspection procedures shall be in accordance with section 4 of MIL-M-38510 to the extent specified in MIL-STD-883 (see 3.1 herein).
- 4.2 <u>Screening</u>. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria shall apply:
  - a. Burn-in test, method 1015 of MIL-STD-883.
    - (1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1015 of MIL-STD-883.
    - (2)  $T_A = +125$ °C, minimum.
  - b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.

TABLE II. <u>Electrical test requirements</u>.

Test requirements	Subgroups (in accordance with method 5005, table I)
Interim electrical parameters (method 5004)	
Final electrical parameters (method 5004)	1*,2,3 7,8,9,10,11
Group A test requirements (method 5005)	1,2,3,4,7, 8,9,10,11
Group C and D end-point electrical parameters (method 5005)	1,2,3

<sup>\*</sup> PDA applies to subgroup 1.

- 4.3 <u>Quality conformance inspection</u>. Quality conformance inspection shall be in accordance with method 5005 of MIL-STD-883 including groups A, B, C, and D inspections. The following additional criteria shall apply.
  - 4.3.1 Group A inspection.
    - a. Tests shall be as specified in table II herein.
    - b. Subgroups 5 and 6 in table I, method 5005 of MIL-STD-883 shall be omitted.
    - c.  $C_{IN}$ ,  $C_{OUT}$ , and  $C_{PD}$  shall be measured only for initial qualification and after process or design changes which may affect capacitance.  $C_{IN}$  and  $C_{OUT}$  shall be measured between the designated terminal and GND at a frequency of 1 MHz.  $C_{PD}$  shall be tested in accordance with the latest revision of JEDEC Standard No. 7-A and table I herein. For  $C_{IN}$ ,  $C_{OUT}$ , and  $C_{PD}$ , test all applicable pins on five devices with zero failures.
    - d. Subgroups 7 and 8 tests shall be sufficient to verify the truth table in figure 2 herein. The test vectors used to verify the truth table shall, at a minimum, test all functions of each input and output. All possible input to output logic patterns per function shall be guaranteed, if not tested, to the truth tables in figure 2 herein.

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- 4.3.2 Groups C and D inspections.
  - a. End-point electrical parameters shall be as specified in table II herein.
  - b. Steady-state life test conditions, method 1005 of MIL-STD-883.
    - (1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1005 of MIL-STD-883.
    - (2)  $T_{\Lambda} = +125^{\circ}C$ , minimum.
    - (3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.
- 4.4 Methods of inspection. Methods of inspection shall be specified as follows:
- 4.4.1 <u>Voltage and current</u>. Unless otherwise specified, all voltages given are referenced to the microcircuit GND terminal. Currents given are conventional current and positive when flowing into the referenced terminal.
  - PACKAGING
  - 5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-M-38510.
  - 6. NOTES
- 6.1 <u>Intended use.</u> Microcircuits conforming to this drawing are intended for use when military specifications do not exist and qualified military devices that will perform the required function are not available for original equipment manufacturer application. When a military specification exists and the product covered by this drawing has been qualified for listing on QPL-38510, the device specified herein will be inactivated and will not be used for new design. The QPL-38510 product shall be the preferred item for all applications.
- 6.2 <u>Replaceability</u>. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.
- 6.3 <u>Configuration control of SMD's</u>. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished in accordance with MIL-STD-481 using DD Form 1693, Engineering Change Proposal (Short Form).
- 6.4 <u>Record of users</u>. Military and industrial users shall inform Defense Electronics Supply Center when a system application requires configuration control and the applicable SMD. DESC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronics devices (FSC 5962) should contact DESC-EC, telephone (513) 296-6047.
- 6.5 Comments. Comments on this drawing should be directed to DESC-EC, Dayton, Ohio 45444, or telephone (513) 296-5377.
- 6.6 <u>Approved sources of supply</u>. Approved sources of supply are listed in MIL-BUL-103. The vendors listed in MIL-BUL-103 have agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DESC-EC.

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